

AMENDMENTS

IN THE CLAIMS:

Please amend claim 1 and add claims 21-26 as follows below.

1. (Currently amended) A chemical mechanical polishing system, comprising:
a platen having a first surface coupling a polishing pad thereto, the first surface comprising a generally circular center portion and an annular portion surrounding the generally circular center portion;
the generally circular center portion enclosing an area and having an attachment surface area that is less than the area enclosed by the generally circular center portion, the attachment surface area coupling an inner portion of the polishing pad to the platen,
wherein a surface of the annular portion has a bond strength to the polishing pad that is greater than a bond strength of the center portion to the polishing pad[.]and;
a liquid slurry delivery apparatus configured to deliver a liquid slurry to a polishing surface of the polishing pad.
2. (Original) The system of claim 1, wherein the attachment surface area is between approximately 30% and 70% of the area.
3. (Original) The system of claim 1, wherein the attachment surface area is approximately 50% of the area.
4. (Original) The system of claim 1, wherein the generally circular center portion is defined by a plurality of grooves formed in the first surface.
5. (Original) The system of claim 4, wherein a configuration of the grooves is selected from the group consisting of parallel, hatched, criss-crossed, concentric, spiral, and random.

6. (Original) The system of claim 1, wherein a depth of grooves is approximately fifteen to twenty mils.

7. (Original) The system of claim 1, wherein a width of grooves is approximately one millimeter and a centerline spacing between grooves is approximately one millimeter.

8. (Original) The system of claim 1, wherein the generally circular center portion is defined by a textured surface selected from the group consisting of a dimpled surface and a brushed surface.

9. (Original) The system of claim 1, further comprising a coating disposed outwardly from the first surface.

10. (Original) The system of claim 1, wherein the platen is formed from stainless steel.

11-16. (Canceled).

17. (Original) A chemical mechanical polishing system, comprising:
a platen for coupling a polishing pad thereto, the platen having a first surface comprising a generally circular center portion and an annular portion surrounding the generally circular center portion;

the generally circular center portion enclosing an area and having a first attachment surface area that is between approximately 30% and 70% of the area enclosed by the generally circular center portion, the first attachment surface area adapted to couple an inner portion of the polishing pad to the platen;

the generally circular center portion having a first fluoropolymer coating disposed outwardly therefrom, the first fluoropolymer coating having a low surface wetting

coefficient;

the annular portion having a second fluoropolymer coating disposed outwardly therefrom, the second fluoropolymer coating having a high surface wetting coefficient; and

wherein the first and second fluoropolymer coatings each have a thickness of between approximately ten mils and approximately twenty mils.

18. (Original) The system of claim 17, wherein the generally circular center portion is defined by a plurality of grooves formed in the first surface, a configuration of the grooves selected from the group consisting of parallel, hatched, criss-crossed, concentric, spiral, and random.

19. (Original) The system of claim 17, wherein a depth of grooves is approximately fifteen to twenty mils, a width of grooves is approximately one millimeter, and a centerline spacing between grooves is approximately one millimeter.

20. (Original) The system of claim 17, wherein the generally circular center portion is defined by a textured surface selected from the group consisting of a dimpled surface and a brushed surface.

21. (New) The system of claim 1, wherein the liquid slurry comprises at least one of acids, small particles of glass, abrasives and chemicals to loosen at least one of metals, oxidation and impurities present on the polished surface of the wafer.

22. (New) The system of claim 1, wherein a lower surface wetting coefficient coating associated with the platen is chemically resistant to the liquid slurry.

23. (New) The system of claim 1, wherein a higher surface wetting coefficient coating associated with the platen is chemically resistant to the liquid slurry.

24. (New) The system of claim 9, wherein the coating is chemically resistant to the liquid slurry.

25. (New) The system of claim 17, wherein the first fluoropolymer coating is chemically resistant to the liquid slurry.

26. (New) The system of claim 17, wherein the second fluoropolymer coating is chemically resistant to the liquid slurry.